

**DUAL P-CHANNEL ENHANCEMENT MODE MOSFET**
**Product Summary**

<b>BV<sub>D1D2</sub></b>	<b>R<sub>D1D2(ON)</sub> Typ.</b>	<b>I<sub>D1D2</sub> T<sub>A</sub> = +25°C</b>
-20V	63mΩ @ V <sub>GS</sub> = -4.5V	-3.2A

**Description**

This new generation MOSFET is designed to minimize the on-state resistance (R<sub>D1D2(ON)</sub>) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

**Applications**

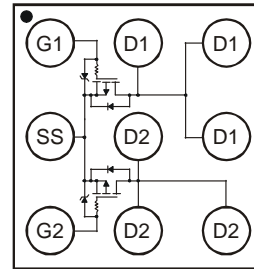
- Battery Management
- Load Switch
- Battery Protection


**Features and Benefits**

- LD-MOS Technology with the Lowest Figure of Merit:
  - R<sub>D1D2(ON)</sub> = 63mΩ to Minimize On-State Losses
  - Q<sub>g</sub> = 3.2nC for Ultra-Fast Switching
- V<sub>GS(TH)</sub> = -0.74V Typ. for a Low Turn-On Potential
- CSP with Footprint 1.5mm × 1.5mm
- Height = 0.62mm for Low Profile
- Gate ESD Protection <HBM Class 3A>
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

**Mechanical Data**

- Case: U-WLB1515-9 (Type E)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal: Finish - SnAgCu. Solderable per MIL-STD-202 Method 208 (e1)
- Terminal Connections: See Diagram Below
- Weight: 0.0018 grams (Approximate)

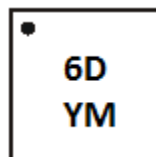


Top View

**Ordering Information** (Note 4)

Part Number	Case	Packaging
DMP2101UCB9-7	U-WLB1515-9 (Type E)	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

**Marking Information**


6D = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: F = 2018)  
 M = Month (ex: 9 = September)

## Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021
Code	C	D	E	F	G	H	I

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-to-Drain Voltage	V <sub>D1D2</sub>	-20	V	
Gate-to-Source Voltage	V <sub>GS</sub>	-6	V	
Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V	I <sub>D1D2</sub>	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	-2.2 -1.7	A
Continuous Drain Current (Note 6) V <sub>GS</sub> = -4.5V		T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	-3.2 -2.5	A
Continuous Source Pin Current (Note 6)	I <sub>S</sub>	-1.6	A	
Pulsed Source Pin Current (Pulse Duration 10μs, Duty Cycle ≤ 1%)	I <sub>SM</sub>	-25	A	
Pulsed Drain Current (Pulse Duration 10μs, Duty Cycle ≤ 1%)	I <sub>DM</sub>	-25	A	

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P <sub>D</sub>	0.74	W
Total Power Dissipation (Note 6)	P <sub>D</sub>	1.56	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	170	°C/W
Thermal Resistance, Junction to Ambient (Note 6)	R <sub>θJA</sub>	81	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 7)</b>						
Drain-to-Drain Breakdown Voltage	BV <sub>D1D2</sub>	-20	—	—	V	V <sub>GS</sub> = 0V, I <sub>D1D2</sub> = -250μA
Zero Gate Voltage Drain Current @T <sub>C</sub> = +25°C	I <sub>DDs</sub>	—	—	-1	μA	V <sub>D1D2</sub> = -16V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	-100	nA	V <sub>GS</sub> = -6V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 7)</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.4	-0.74	-0.9	V	V <sub>D1D2</sub> = V <sub>GS</sub> , I <sub>DS</sub> = -250μA
Static Drain-to-Drain On-Resistance	R <sub>D1D2(ON)</sub>	—	63	100	mΩ	V <sub>GS</sub> = -4.5V, I <sub>D1D2</sub> = -1A
		—	72	130		V <sub>GS</sub> = -2.5V, I <sub>D1D2</sub> = -1A
		—	87	175		V <sub>GS</sub> = -1.8V, I <sub>D1D2</sub> = -1A
<b>DIODE CHARACTERISTICS</b>						
Diode Forward Voltage (Note 6)	V <sub>SD</sub>	—	-0.7	-1	V	V <sub>GS</sub> = 0V, I <sub>D1D2</sub> = -1A
Reverse Recovery Charge	Q <sub>RR</sub>	—	4.1	—	nC	V <sub>D1D2</sub> = -9.5V, I <sub>F</sub> = -1A,
Reverse Recovery Time	t <sub>RR</sub>	—	10.5	—	ns	di/dt = 200A/μs
<b>DYNAMIC CHARACTERISTICS (Note 8)</b>						
Input Capacitance	C <sub>iss</sub>	—	392	588	pF	V <sub>D1D2</sub> = -10V, V <sub>GS</sub> = 0V, f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	183	274	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	8.4	12.6	pF	
Series Gate Resistance	R <sub>g</sub>	—	5.2	10	Ω	V <sub>GS</sub> = 0V, V <sub>D1D2</sub> = 0V, f = 1.0MHz
Total Gate Charge (-4.5V)	Q <sub>g</sub>	—	3.2	4.8	nC	V <sub>GS</sub> = -4.5V, V <sub>D1D2</sub> = -10V, I <sub>D1D2</sub> = -1A
Gate-Source Charge	Q <sub>gs</sub>	—	0.3	—	nC	
Gate-Drain Charge	Q <sub>gd</sub>	—	0.6	—	nC	
Gate Charge at V <sub>th</sub>	Q <sub>g(th)</sub>	—	0.18	—	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	—	3.6	7	ns	V <sub>D1D2</sub> = -10V, V <sub>GS</sub> = -4.5V, I <sub>D1D2</sub> = -1A, R <sub>G</sub> = 30Ω
Turn-On Rise Time	t <sub>R</sub>	—	5.3	—	ns	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	—	40	80	ns	
Turn-Off Fall Time	t <sub>F</sub>	—	20	—	ns	

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout.
  - Device mounted on FR-4 material with 1-inch<sup>2</sup> (6.45-cm<sup>2</sup>), 2-oz. (0.071-mm thick) Cu.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to production testing.

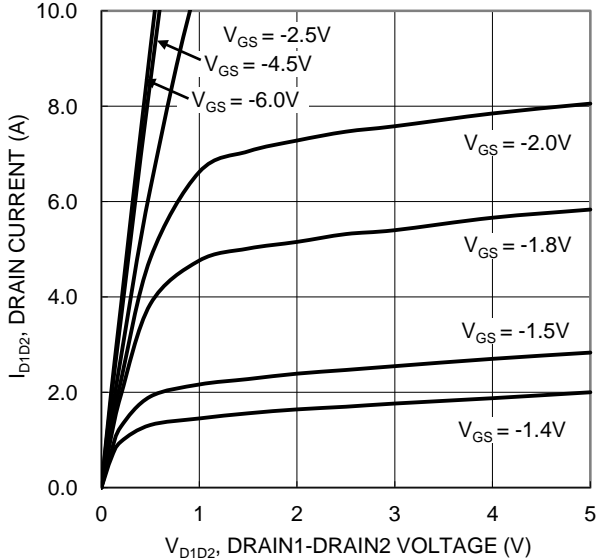


Figure 1. Typical Output Characteristic

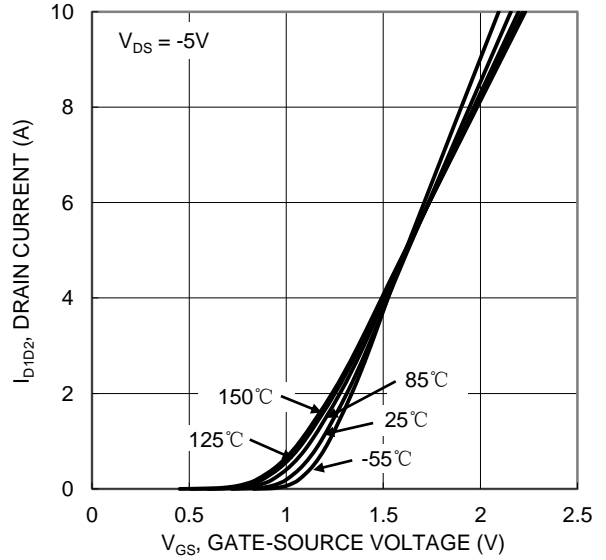


Figure 2. Typical Transfer Characteristic

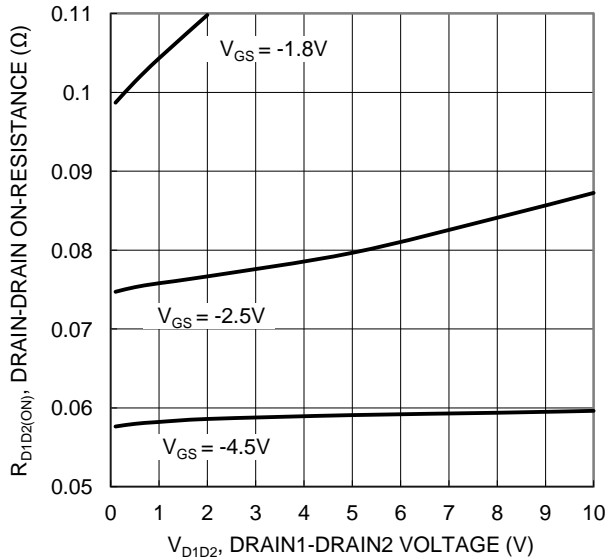


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

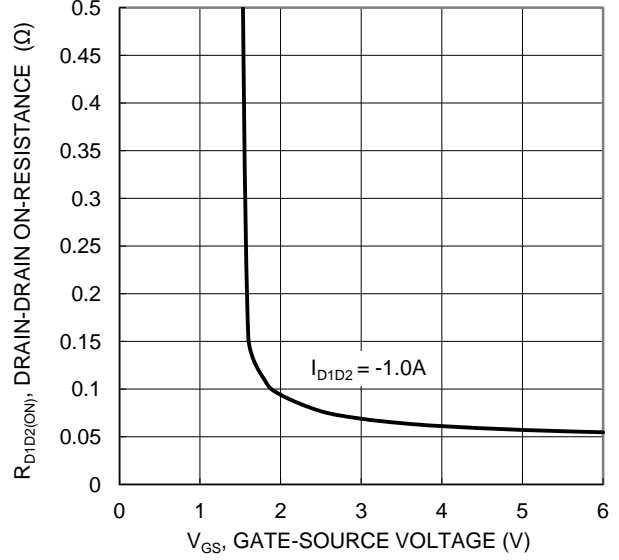


Figure 4. Typical Transfer Characteristic

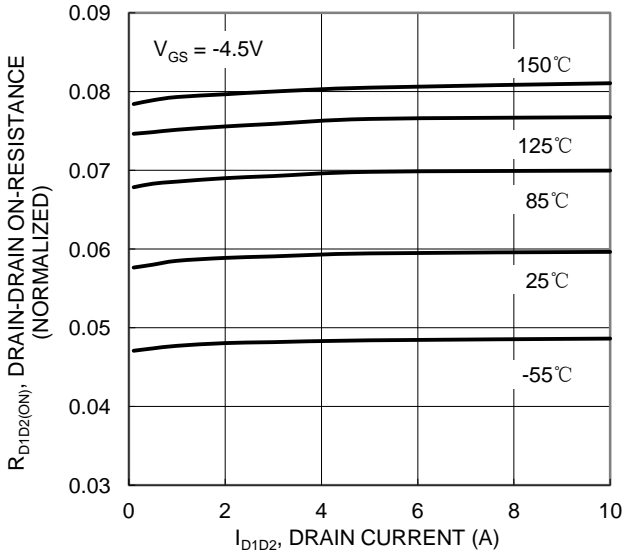


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

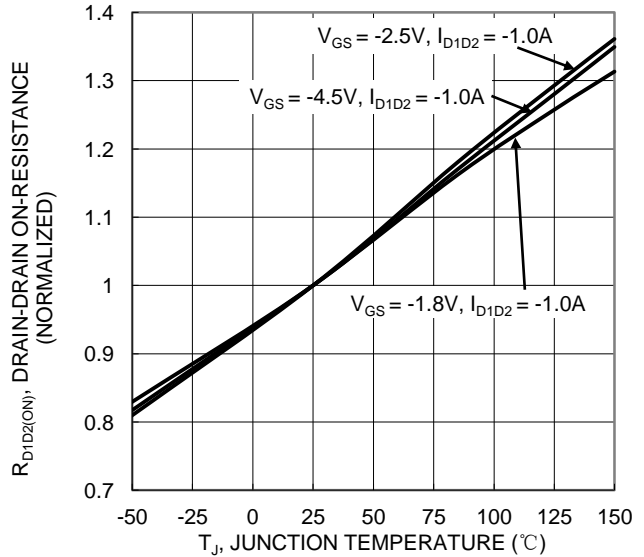


Figure 6. On-Resistance Variation with Junction Temperature

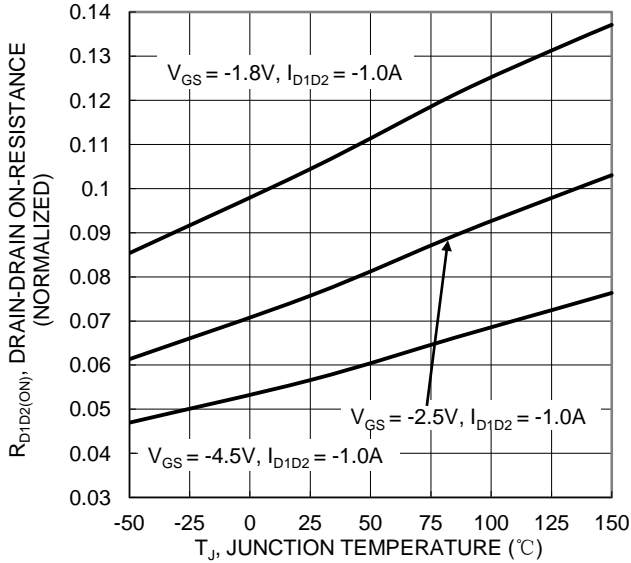


Figure 7. On-Resistance Variation with Junction Temperature

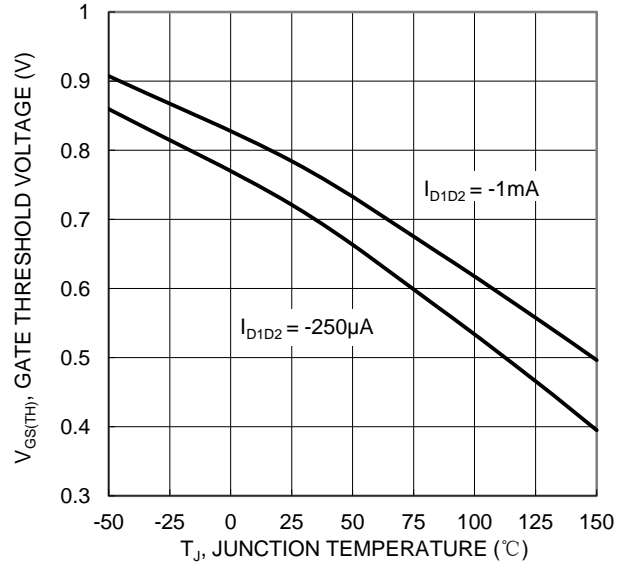


Figure 8. Gate Threshold Variation vs. Junction Temperature

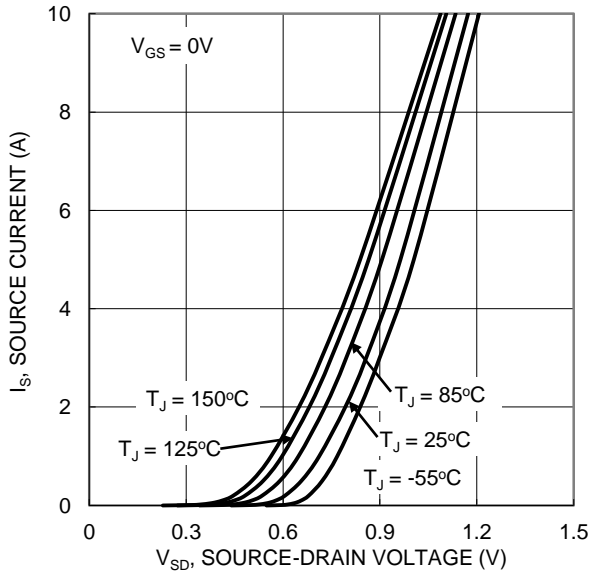


Figure 9. Diode Forward Voltage vs. Current

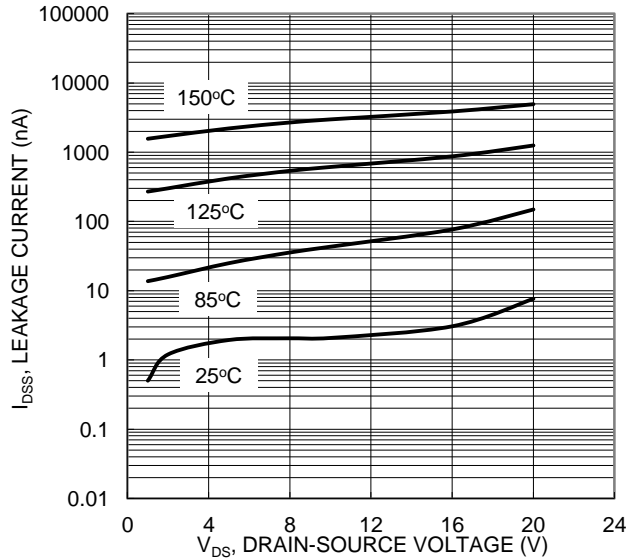


Figure 10. Typical Drain-Source Leakage Current vs. Voltage

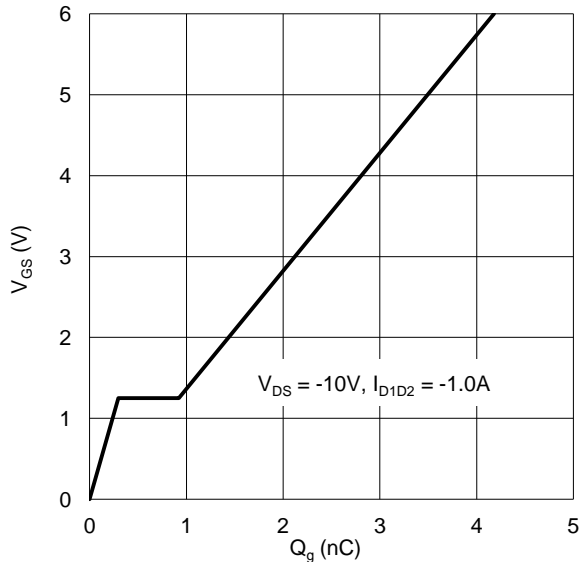


Figure 11. Gate Charge

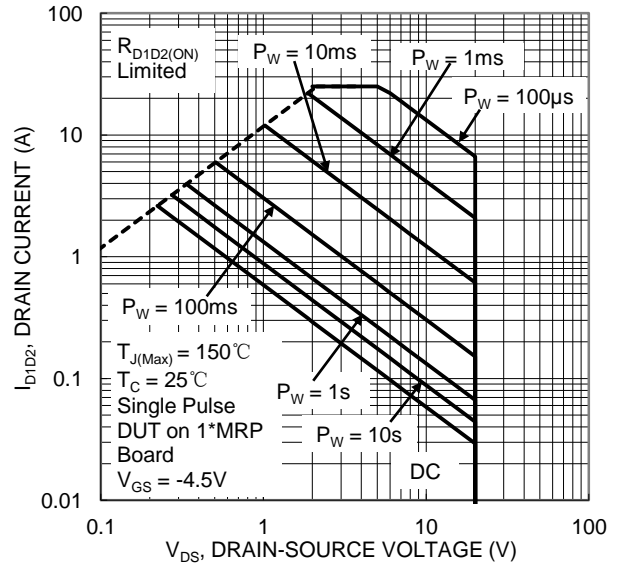


Figure 12. SOA, Safe Operation Area

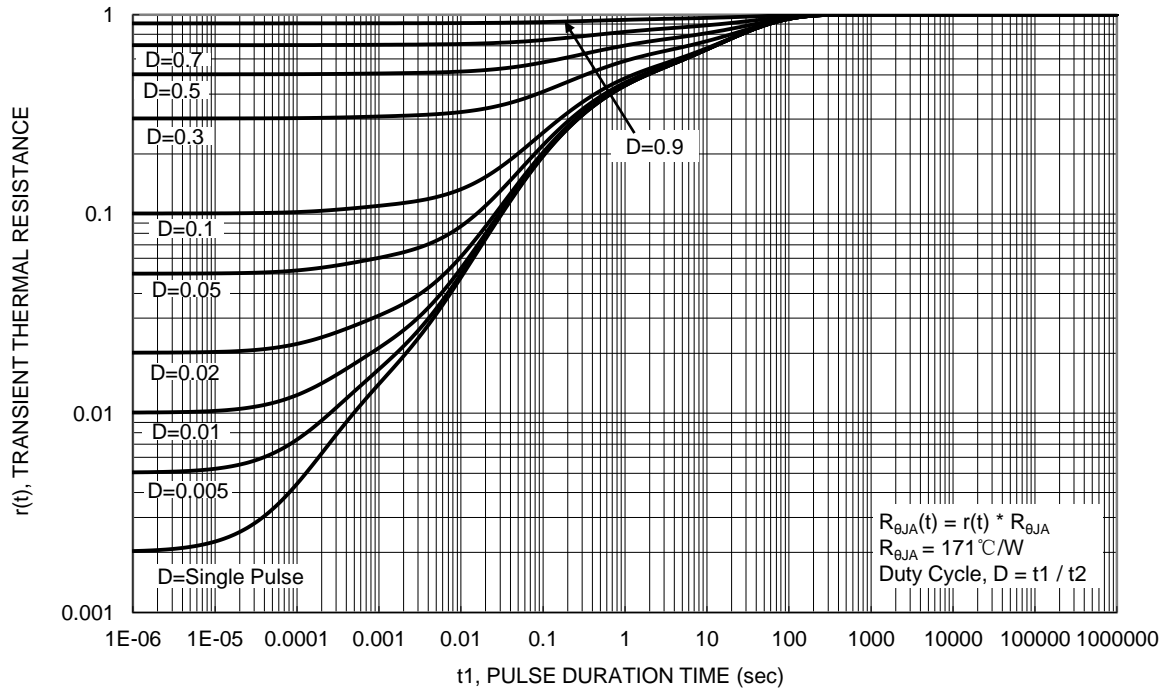
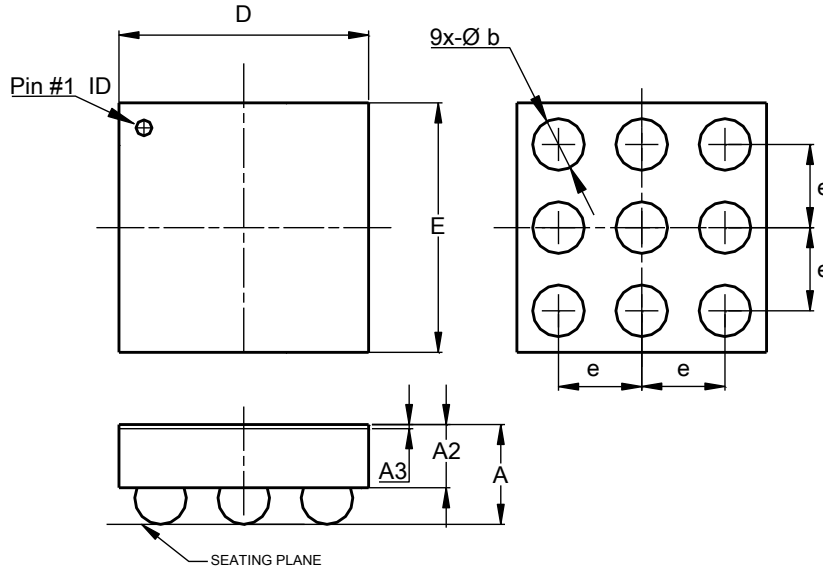


Figure 13. Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**U-WLB1515-9 (Type E)**

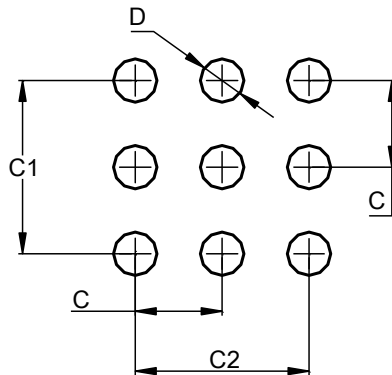


U-WLB1515-9 (Type E)			
Dim	Min	Max	Typ
A	--	0.62	--
A2	--	0.36	0.36
A3	0.020	0.030	0.025
b	0.27	0.37	0.32
D	1.47	1.51	1.49
E	1.47	1.51	1.49
e	--	--	0.50
All Dimensions in mm			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**U-WLB1515-9 (Type E)**



Dimensions	Value (in mm)
C	0.50
C1	1.00
C2	1.00
D	0.25

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